

ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

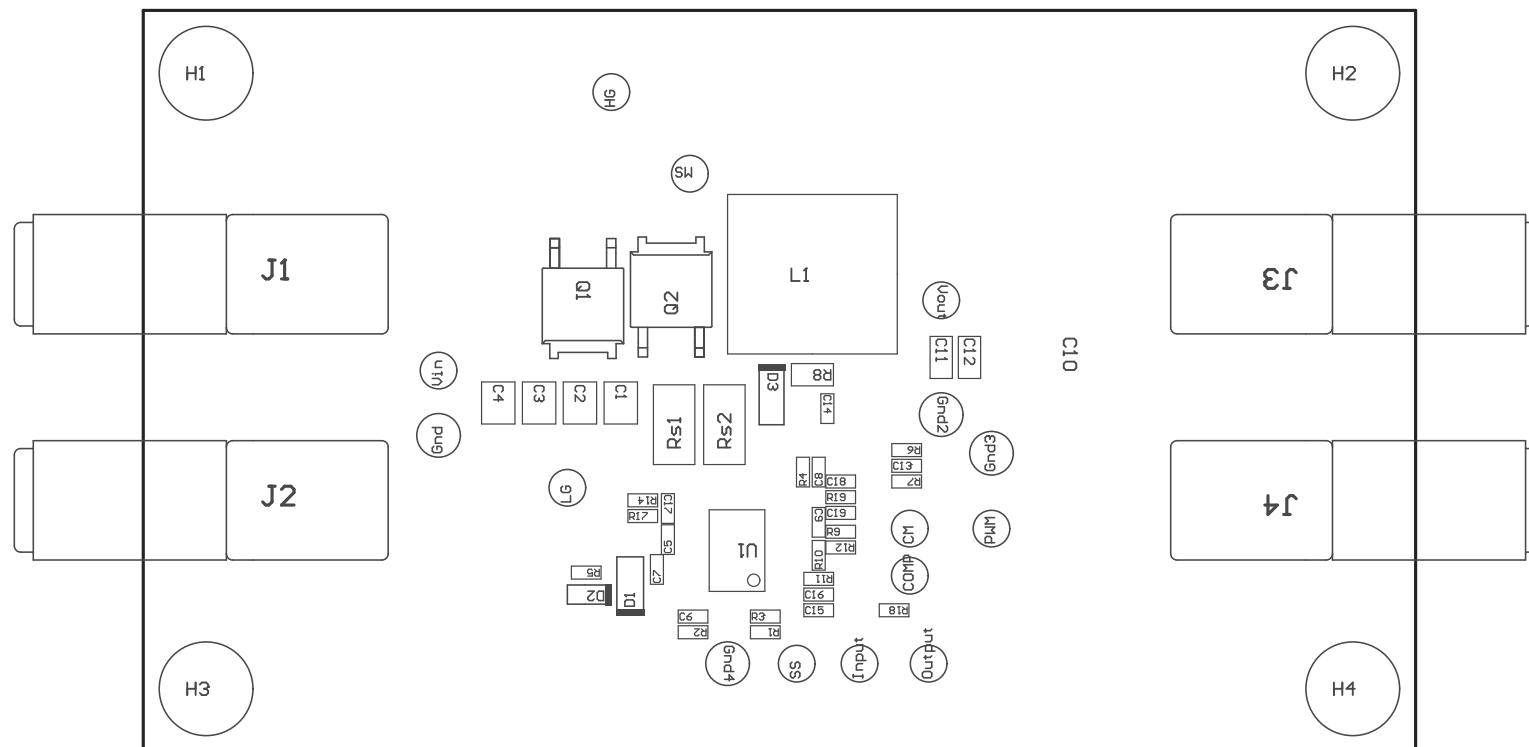
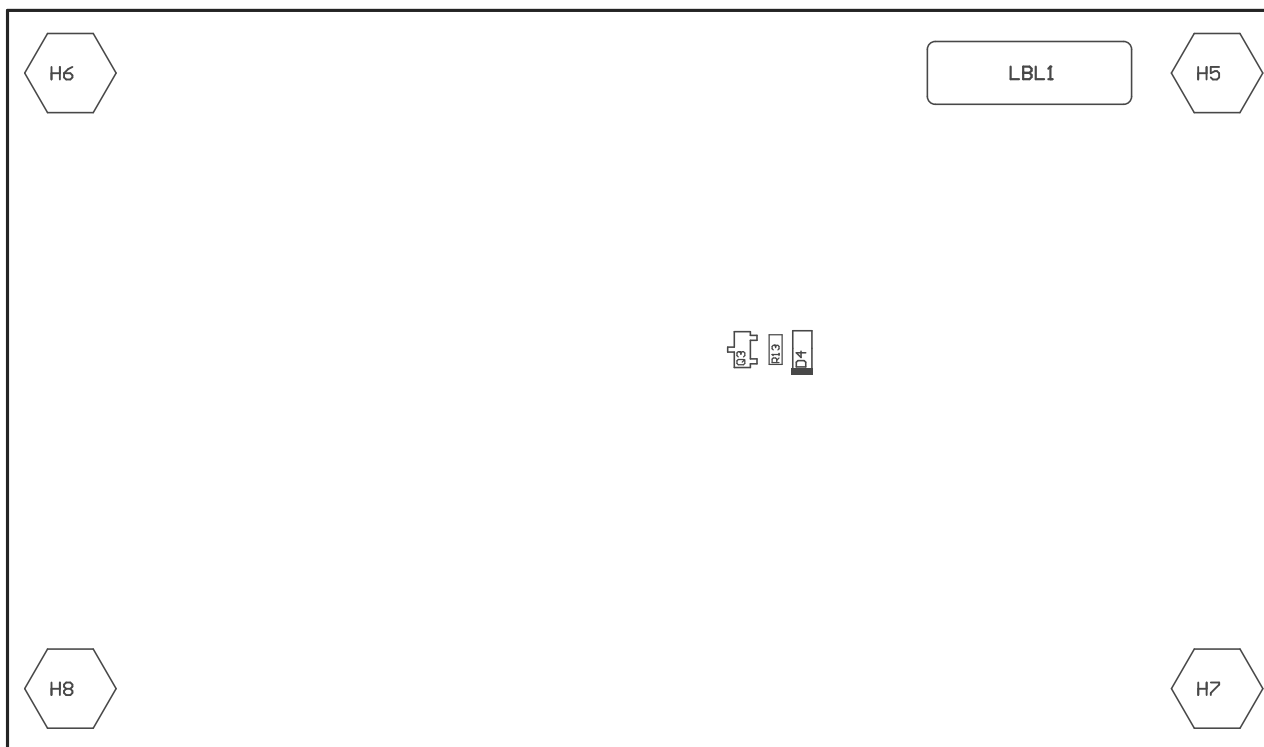


TABLE 1

Variant	Label text
001	

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 11/30/2017 6:38:55 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/30/2017 6:38:56 PM	TEXAS INSTRUMENTS	

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